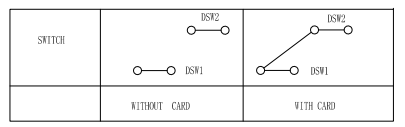
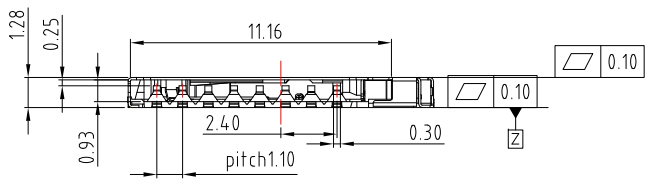


PAD AREA
 KEEP OUT AREA
 GND PATTERN ONLY

PCB LAYOUT



PIN NO.	PIN ASSIGNMENT
P1	DAT2
P2	CD/DAT3
P3	CMD
P4	VDD
P5	CLK
P6	VSS
P7	DAT0
P8	DAT1

SPECIFICATION

- Electrical :
- 1.Current Rating: 0.5A AC / DC Max
 - 2.Voltage Rating: 12V AC / DC
 - 3.Contact Resistance: 100 mΩ Max.
 - 4.Insulation Resistance: 1000 MΩ Min.

Material:

- 1.Housing: LCP
- 2.Contact: Phosphor Bronze
- 3.Shell: SUS

Finish:

- 1.Contact: Plated Gold in Mating Area ;
Gold Plated on Solder Balls ;
Nickel under plated overall
- 2.Shell: Nickel under Plated surface layer

ITEM NO.	DESCRIPTION	DRAWN	DATE
5	更新Contact材質	Jack	071724
4	更新樣式和材質	Jack	071624
3	更新PCB LAYOUT方向	Jack	012324
2	更新料號	Jack	112421
1	更新料號	Jack	112321

CONTACT 建倚科技股份有限公司
CONTACT TECHNOLOGY CORP.

TOLERANCE UNLESS OTHERWISE STATED :

Up to 5	±0.2
Above 5 ~ 15	±0.3
Above 15 ~ 30	±0.4
Above 30 ~ 50	±0.5
Angle	±0.3°

3RD. ANGEL'S

DRAWN BY:	DATE	MAT'L	TITLE	CONTRACTOR
Jack Lu	07/17/24		CONNECTOR	
CHECKED BY:	DATE	FINISH	MODLE	MICRO SD CARD PUSH PUSH H1.28
Jacky Chen	07/17/24			
APPROVED BY:	DATE	SCALE	DWG NO.	SD-TF128-S267
Tony Kao	07/17/24	1 : 1		
SHEET NO.	1 of 1	PART NO.	SD-TF128-S267	
				SIZE A4
				VER R6